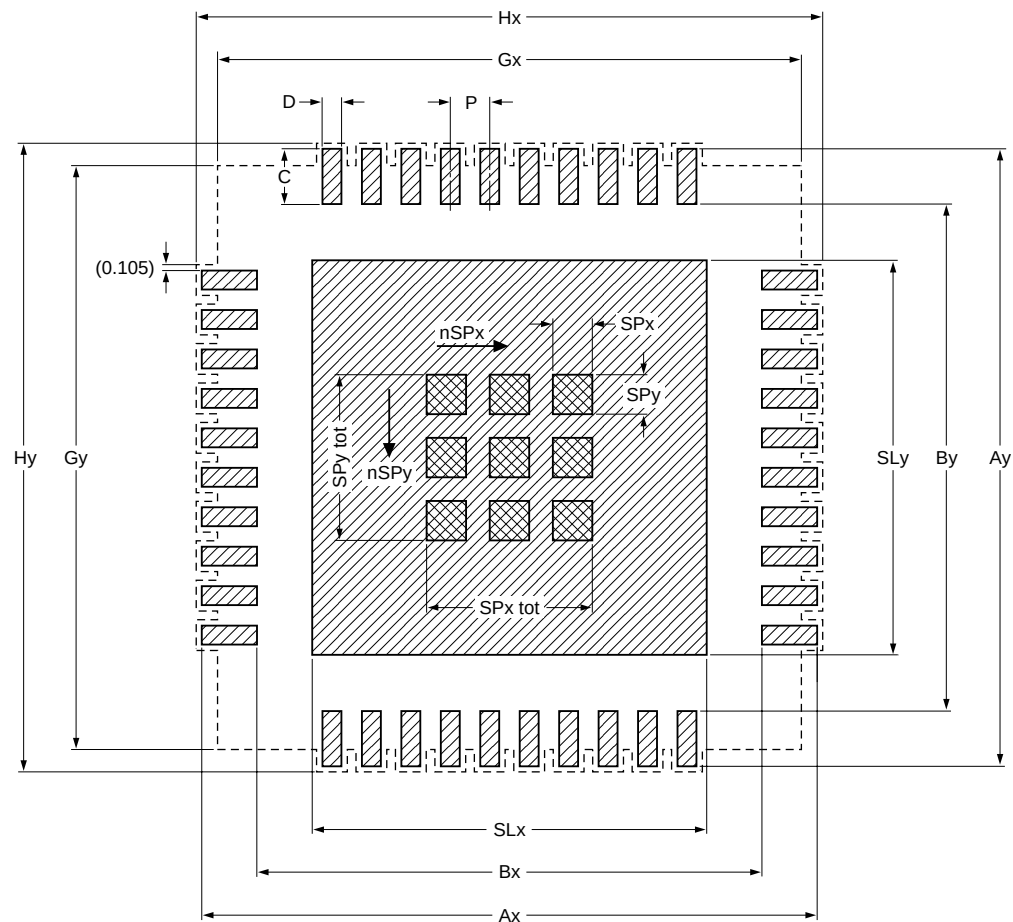


Footprint information for reflow soldering of HVQFN48 package

SOT778-1



- Generic footprint pattern
Refer to the package outline drawing for actual layout
- solder land
 - solder paste deposit
 - solder land plus solder paste
 - occupied area

nSPx	nSPy
3	3

DIMENSIONS in mm

P	Ax	Ay	Bx	By	C	D	SLx	SLy	SPx tot	SPy tot	SPx	SPy	Gx	Gy	Hx	Hy
0.400	7.000	7.000	5.200	5.200	0.900	0.230	4.100	4.100	2.400	2.400	0.600	0.600	6.300	6.300	7.250	7.250